

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Takashi HIROI</td> <td>05/17/2007</td> </tr> <tr> <td>Kenji TANIMOTO</td> <td>05/17/2007</td> </tr> <tr> <td>Yuko SASAKI</td> <td>05/18/2007</td> </tr> <tr> <td>Hiroshi MAKINO</td> <td>05/17/2007</td> </tr> </tbody> </table>		Name	Execution Date	Takashi HIROI	05/17/2007	Kenji TANIMOTO	05/17/2007	Yuko SASAKI	05/18/2007	Hiroshi MAKINO	05/17/2007
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Yuko SASAKI	05/18/2007										
Hiroshi MAKINO	05/17/2007										
RECEIVING PARTY DATA											
Name:	Hitachi High-Technologies Corporation										
Street Address:	1-24-14, Nishi Shinbashi,										
City:	Minato-ku, Tokyo										
State/Country:	JAPAN										
PROPERTY NUMBERS Total: 1											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11808247</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11808247						
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CORRESPONDENCE DATA											
Fax Number:	(202)628-8844										
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Total Attachments: 1 source=59168USAssignment#page1.tif											

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PATENT

500335077

REEL: 019697 FRAME: 0867

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation, a corporation organized under the laws of Japan, located at 1-24-14, Nishi Shinbashi, Minato-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR WAFER INSPECTION TOOL AND SEMICONDUCTOR WAFER INSPECTION METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Takashi Hiroo</u>	<u>5/17/2007</u>
2) <u>Kenji Yamamoto</u>	<u>5/17/2007</u>
3) <u>Yuko Sasaki</u>	<u>5/18/2007</u>
4) <u>Hiashi Makino</u>	<u>5/17/2007</u>
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____